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*PROCEEDINGS OF THE*

**34<sup>TH</sup> INTERNATIONAL  
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TECHNOLOGY CONFERENCE  
(IEMT 2010)**

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*Tan Kian Heong & Fuaida Harun*

Infineon Technologies Sdn. Bhd., MALAYSIA

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##### **Development of Copper-Copper Bonding by Ultrasonic Welding for IGBT Modules "6: :**

*Kazumasa Kido, Fumihiko Momose, Yoshitaka Nishimura & Tomoaki Goto*

Fuji Electric Systems Co. Ltd., JAPAN

#### **D5.4**

##### **A Tiny SO Package Cu Wire Neck Fatigue Fracturing Elimination "6; 5**

*Song Xiaoqing, Wei Haili & Zhao Hongbin*

Leshan Phoenix Semiconductor Co. Ltd., CHINA

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*Low Khai Yen Charles*

Infineon Technologies Sdn. Bhd., MALAYSIA

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*Nor Azlian Abdul Manaf, Mohd Sharizal Alias, Sufian Mousa Mitani & Farha Maskuriy*

Telekom Malaysia Research and Development, MALAYSIA

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*Chan Wai Ti<sup>1</sup>, Dr. Ir. Sim Kok Swee<sup>1</sup> & Dr. Tso Chih Ping<sup>2</sup>*

<sup>1</sup>Multimedia University, MALAYSIA

<sup>2</sup>Nanyang Technological University, SINGAPORE

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*Mohd Sofwan Mohd Resali*

University Tenaga National, MALAYSIA

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*Ng Hong Seng*

X-FAB Sarawak Sdn. Bhd., MALAYSIA

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*Chia Saw Ean*

Intel Technology Sdn. Bhd., MALAYSIA

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*Octovia Peter*

Intel Technology Sdn. Bhd., MALAYSIA

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*Dr. John H Lau*

ITRI, TAIWAN

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*Dr. Ho Hong Meng*

Semicon Fine Wire, SINGAPORE

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**Past, Present and Future of Electronic Packaging "758**

*Dr. Joseph Fjelstad*

Verdant Electronics, USA

**MAWAR ROOM (HALF DAY)**

**Flip Chip Technology "75:**

*Dr. Yutaka Tsukada*

Ritsumeikan/Osaka University, i-PACKS, JAPAN

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*Dr. Rolf Aschenbrenner*

Fraunhofer Institute, GERMANY

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*Kim Hyland*

CISCO, USA

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*Dr. Yutaka Tsukada*

Ritsumeikan/Osaka University, i-PACKS, JAPAN

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*Dr. William Chen*

ASE Inc., USA

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*Knoblauch Andreas*

Infineon, GERMANY

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*Xavier Baraton*

ST Microelectronics, SINGAPORE

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*Dr. Joe Fjelstad*

Verdant Electronics, USA

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*CS Liu*

National Semiconductor, USA



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*Dr. Yutaka Tsukada*

Ritsumeikan/Osaka University, i-PACKS, JAPAN

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*John Hunt*

ASE Inc, USA

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*Shankar Shridhar*

EQIS, AUSTRALIA

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*Amir Nur Rashid Wagiman*

Intel Technologies Sdn. Bhd., MALAYSIA